

LMP2165RF 20V P-Channel Enhancement MOSFET

Features

- $R_{DS(ON)} = 65m\Omega @ V_{GS} = -4.5V$
- Improved dv/dt capability
- Fast switching
- Suit for -1.8V Gate Drive Applications
- Green Device Available
- SOT-23-6L package design

These devices are particularly suited for high efficiency fast switching applications.

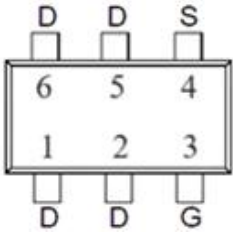
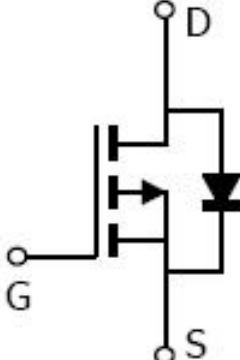
Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

Applications

- Notebook
- Load Switch
- Hand-held Instruments

Pin Configuration

LMP2165RF (SOT-23-6L)		 Top Views
Pin	Description	
1	Drain	
2	Drain	
3	Gate	
4	Source	
5	Drain	
6	Drain	

Ordering Information

Part Number	P/N	PKG Code	Pb Free Code	Package	Quantity Reel
LMP2165RF	LMP2165	R	F	SOT-23-6L	3000 pcs

Marking Information

Part Marking	Part Number	LFC code
P1 XWM	P1	XWM

Absolute Maximum Ratings

(T_A=25°C Unless otherwise noted)

Symbol	Parameter		Typical	Unit
V _{DS}	Drain-Source Voltage		-20	V
V _{GS}	Gate-Source Voltage		±12	V
I _D	Continuous Drain Current ¹	T _A =25°C	-3.5	A
		T _A =70°C	-2.6	
I _{DM}	Pulsed Drain Current ²		-12	A
P _D	Total Power Dissipation ³	T _A =25°C	1.25	W
		T _A =70°C	0.8	
T _J	Operating Junction Temperature Range		-55 to +150	°C
T _{STG}	Storage Temperature Range		-55 to +150	°C
R _{θJA}	Thermal Resistance-Junction to Ambient		100	°C/W

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2oz copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. The power dissipation is limited by 150°C junction temperature.

Electrical Characteristics

(T_A=25°C Unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-20			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	-0.4		-0.9	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±12V			±100	nA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-20V, V _{GS} =0V			-1	uA
I _S	Continuous Source Current	V _G =V _D =0V, Force Current			-4.1	A
I _{SM}	Pulsed Source Current				-8.2	
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-4.5A		59	65	mΩ
		V _{GS} =-2.5V, I _D =-3A		80	85	
		V _{GS} =-1.8V, I _D =-1.5A		110	130	
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-4.5A		10		S
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-1A		-0.8	-1.2	V
Dynamic						
C _{iss}	Input Capacitance	V _{DS} =-10V, V _{GS} =0V, f=1MHz		515		pF
C _{oss}	Output Capacitance			55		
C _{rss}	Reverse Transfer Capacitance			20		
Q _g	Total Gate Charge ^{4,5}	V _{DS} =-10V, V _{GS} =-4.5V, I _D =-3A		6.4		nC
Q _{gs}	Gate-Source Charge ^{4,5}			0.9		
Q _{gd}	Gate-Drain Charge ^{4,5}			1.6		
t _{d(on)}	Turn-On Delay Time ^{4,5}	V _{DD} =-10V, I _D =-1A, V _{GS} =-4.5V, R _G =25Ω		5		ns
T _r	Turn-On Rise Time ^{4,5}			17.4		
t _{d(off)}	Turn-Off Delay Time ^{4,5}			40.7		
T _f	Turn-Off Fall Time ^{4,5}			11.4		

Note:

4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.

5. Essentially independent of operating temperature..

Typical Performance Characteristics

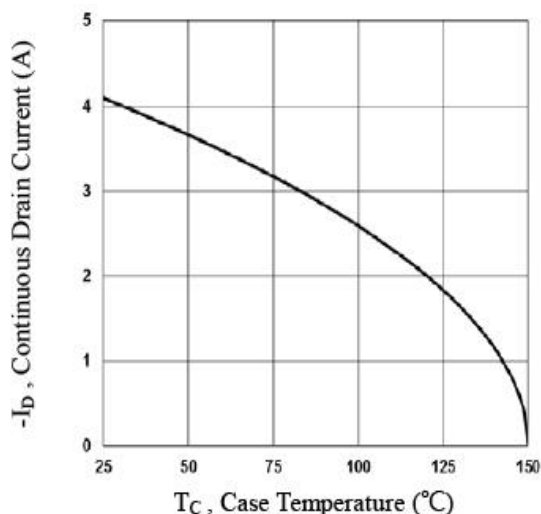
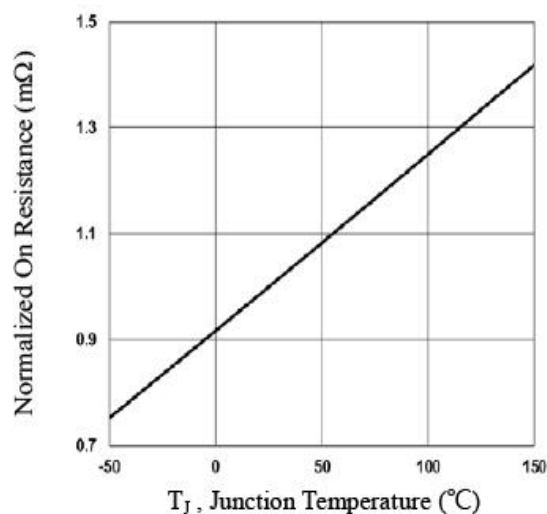
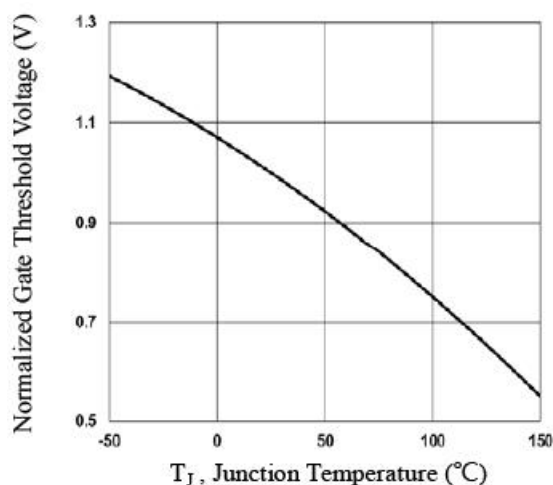
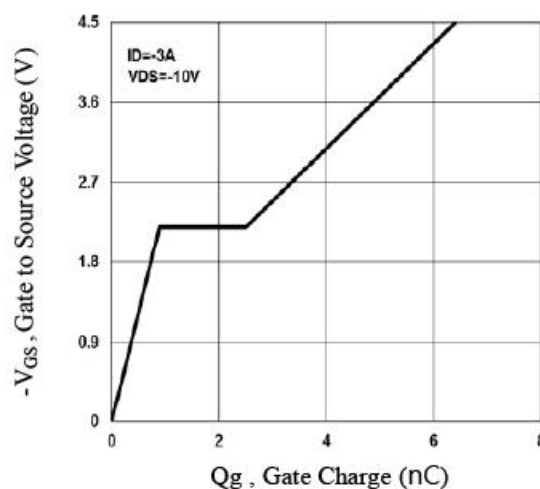

Fig.1 Continuous Drain Current vs T_C

Fig.2 Normalized $R_{DS(on)}$ vs T_J

Fig.3 Normalized V_{TH} vs T_J


Fig.4 Gate Charge Waveform

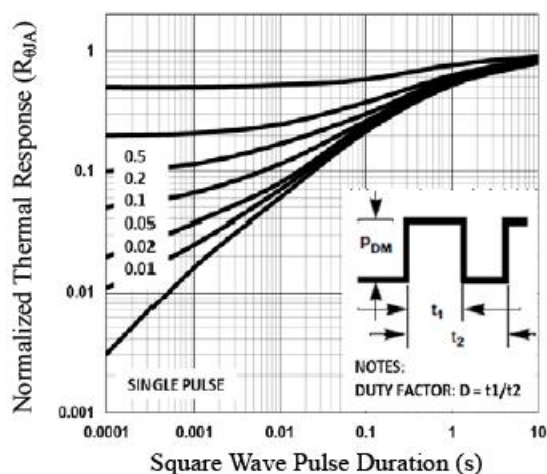


Fig.5 Normalized Transient Impedance

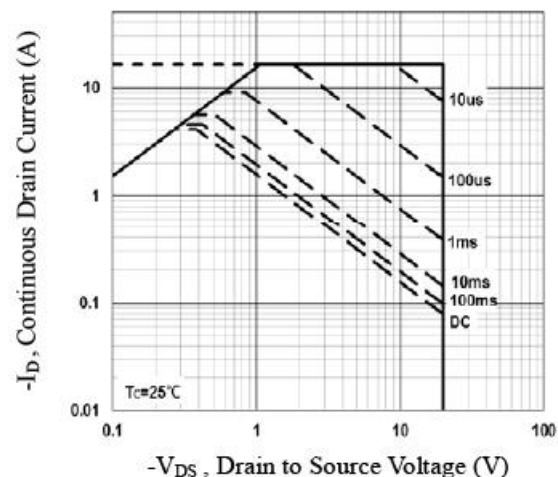
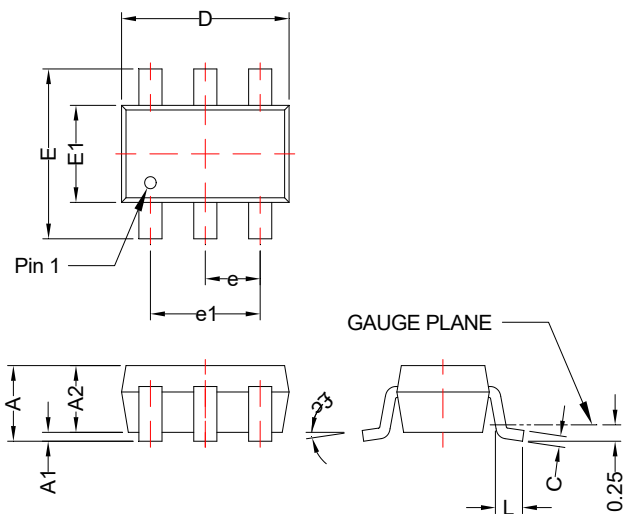


Fig.6 Maximum Safe Operating Area

Package Dimension
SOT-23-6L


Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.900	1.450	0.035	0.057
A1	0.000	0.150	0.000	0.006
A2	0.900	1.300	0.035	0.051
b	0.300	0.500	0.012	0.020
c	0.080	0.260	0.003	0.010
D	2.700	3.100	0.106	0.122
E	2.200	3.000	0.087	0.118
E1	1.300	1.750	0.051	0.069
e	0.950 BSC		0.037 BSC	
e1	1.900 BSC		0.075 BSC	
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°